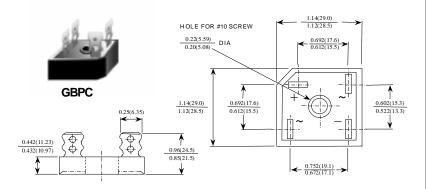


Discrete POWER & Signal Technologies

GBPC 12, 15, 25, 35 SERIES

Features

- Integrally molded heatsink provided very low thermal resistance for maximum heat dissipation.
- Surge overload rartings from 300 amperes to 400 amperes.
- Isolated voltage from case to lead over 2500 volts.

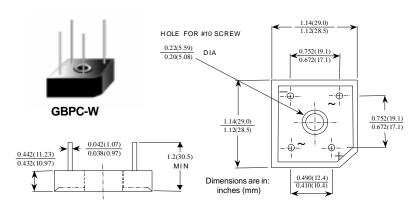


Suffix "W"

Wire Lead Structure

Suffix "M"

Terminal Location Face to Face



12, 15, 25, 35 Ampere Glass Passivated Bridge Rectifiers

Absolute Maximum Ratings* T_A

 $T_A = 25$ °C unless otherwise noted

Symbol	Parameter	Value	Units	
lo	Averag e Rectified Curr ent GBPC12	12	Α	
	$@T_A = 55^{\circ}C$ GBPCI5	15	Α	
	GBPC25	25	Α	
	GBPC35	35	Α	
i _{f(surge)}	Peak F or ward Surge C urrent			
(3-)	8.3 ms single half- sine-wave GBPC12, 15, 25	300	Α	
	Superimposed on rate d load (JEDEC method GBPC35	400	Α	
P _D	Total D evice Dissipati on	83.3	W	
	Derate above 25C	666	mW/°C	
$R_{\theta JL}$	Ther mal Resistance, Junction to Lead	1.5	°C/W	
T _{stg}	Storag e Temperature Range	-55 to +150	°C	
TJ	Operati ng Junction Temperature	-55 to +1	50 °C	

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Glass Passivated Bridge Rectifiers

(continued)

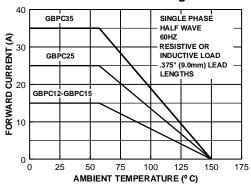
Electrical Characteristics

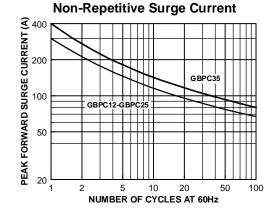
T_A = 25°C unless otherwise noted

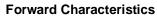
Parameter		Device						Units
	005	01	02	04	06	08	10	
Peak Repetitive Reverse Voltage	50	100	200	400	600	800	1000	V
Maximum RMS Bridge Input Voltage	35	70	140	280	420	560	700	V
DC Reverse Voltage (Rated V _R)	50	100	200	400	600	800	1000	V
Maximum Reverse Leakage, total bridge @ rated V_R $T_A = 25^{\circ}C$ $T_A = 125^{\circ}C$				5.0 500				μA μA
Maximum Forward Voltage Drop, per bridge @ 6.0 A GBPC12 @ 7.5 A GBPC15 @ 12.5 A GBPC25 @ 17.5 A GBPC35		1.1						V
I^2 t rating for fusing t < 8.3 ms GBPC12,15,25 GBPC35		375 660						A ² Sec A ² Sec
Typical Junction Capacitance, per let $V_R = 4.0V$, $GBPC12,15,25$ $f = 1.0 \ MHz$ $GBPC35$		180 200					pF pF	

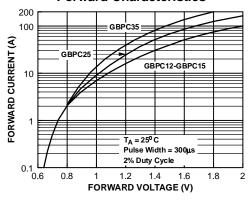
Typical Characteristics

Forward Current Derating Curve

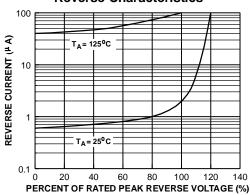








Reverse Characteristics



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FACT Quiet Series $^{\text{TM}}$ Quiet Series $^{\text{TM}}$ SuperSOT $^{\text{TM}}$ -3 SuperSOT $^{\text{TM}}$ -6 GTO $^{\text{TM}}$ SuperSOT $^{\text{TM}}$ -8 HiSeC $^{\text{TM}}$ TinyLogic $^{\text{TM}}$

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PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
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